

AOD425A-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.018 at V _{GS} = - 10 V	- 40	13 nC			
- 30	0.025 at V _{GS} = - 4.5 V	- 35	13110			

FEATURES

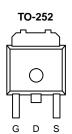
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested

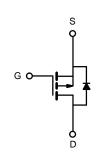




APPLICATIONS

- Load Switch
- · Battery Switch





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	$_{A}$ = 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20	v	
	T _C = 25 °C		- 40	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 35	
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	I _D	- 30.0 ^{a, b}	
	T _A = 70 °C		- 28 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 150		
0 (0 0 0 0 0 0 0	T _C = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.1 ^{a, b}	
	T _C = 25 °C		40	
Maximum Davin Dissination	T _C = 70 °C		27	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on $T_C = 25$ °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 31		m\//°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = - 250 μΑ		4.5		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltago Droin Current		V _{DS} = - 30 V, V _{GS} = 0 V			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 5	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 40			Α
Davis Course Co Otata Basista and	D	V _{GS} = - 10 V, I _D = - 7.0 A		0.018		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5.6 A		0.025		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S
Dynamic ^b						
Input Capacitance	C _{iss}			1455		pF
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		
Reverse Transfer Capacitance	C _{rss}			145		
Total Cata Charma	Q_g $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -7.0 \text{ A}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	
Total Gate Charge			13	20	1	
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		- nC
Gate-Drain Charge	Q_{gd}			5.5		
Gate Resistance	R _g	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		13	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_q = 1 \Omega$		23	35	
Fall Time	t _f	-		9	18	
Turn-On Delay Time	t _{d(on)}			38	57	ns
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		89	134	1
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33	1
Fall Time	t _f			11	17	1
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5	^
Pulse Diode Forward Current	I _{SM}				- 30	A
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = FG A dl/dt = 100 A/vo T = 25 °C		17	26	nC
Reverse Recovery Fall Time	t _a	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13		ns
Reverse Recovery Rise Time	t _b			9		

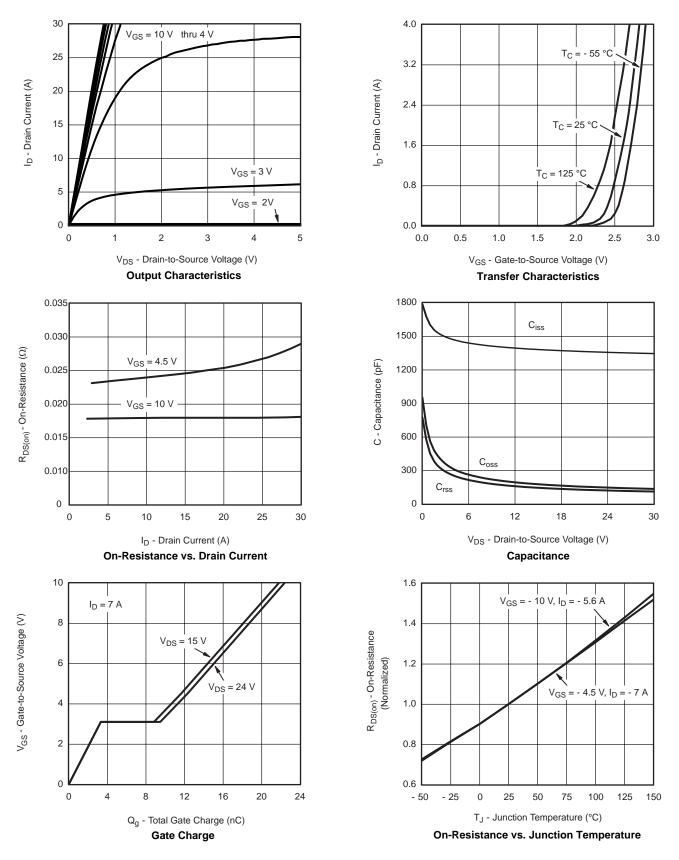
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

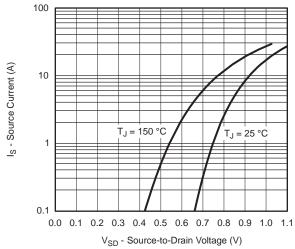
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

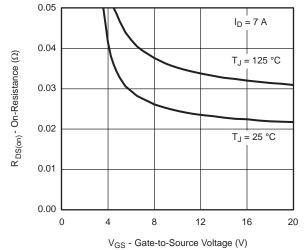




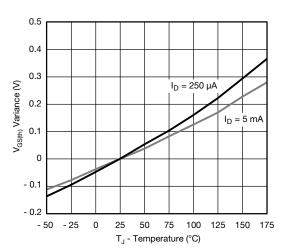




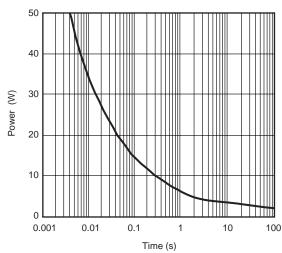
Source-Drain Diode Forward Voltage



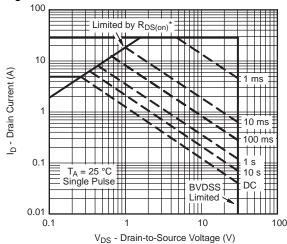
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



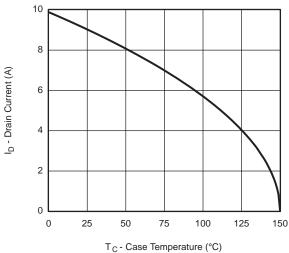
Single Pulse Power, Junction-to-Ambient



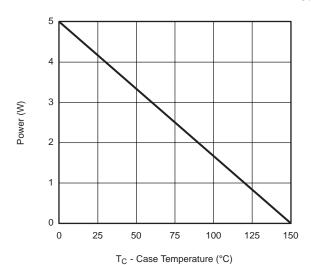
* $V_{GS} > \mbox{ minimum } V_{GS}$ at which $R_{DS(on)}$ is specified

Safe Operating Area

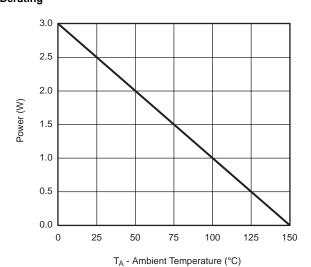




Current Derating*



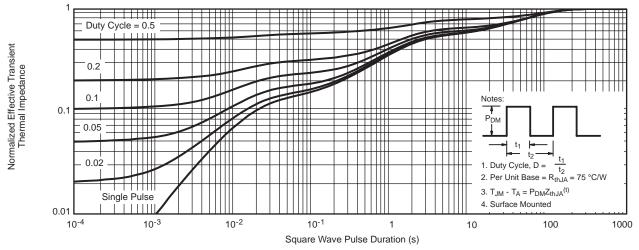
Power, Junction-to-Foot



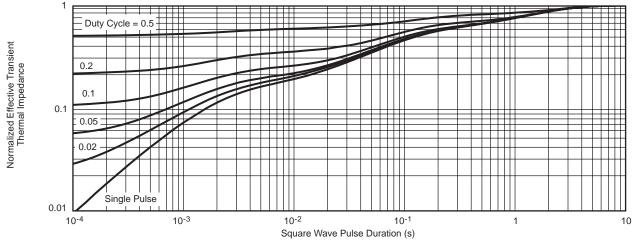
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





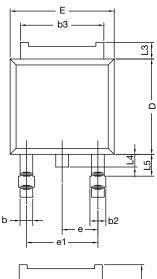
Normalized Thermal Transient Impedance, Junction-to-Ambient

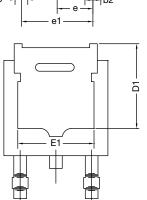


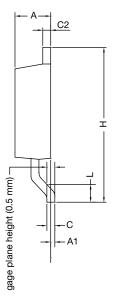
Normalized Thermal Transient Impedance, Junction-to-Foot



TO-252AA CASE OUTLINE







	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	2.28 BSC		BSC	
e1	4.56	4.56 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M. 24-Dec-12					

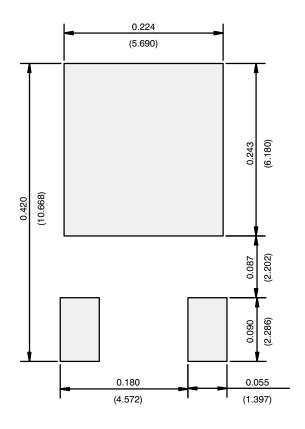
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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